

AOWF2606-VB Datasheet N-Channel 60 V (D-S) MOSFET

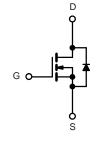
PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	l _D (A) ^a		
60	0.003 at V _{GS} = 10 V	210		
00	0.005 at V _{GS} = 4.5 V	185		

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Gate-Source Voltage		V _{GS}	± 20	V		
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C	1-	210			
	T _C = 100 °C	I _D	185 ^a			
Pulsed Drain Current		I _{DM}	200	А		
Continuous Source Current (Diode Conduction)	۱ _S	180 ^a				
Avalanche Current	I _{AS}	70				
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	125	mJ		
Maximum Dawar Dissinction	T _C = 25 °C	P _D	136	W		
Maximum Power Dissipation	T _A = 25 °C		3 ^b , 8.3 ^{b, c}	vv		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	$t \le 10 \text{ sec}$	- R _{thJA}	15	18	°C/W	
	Steady State		40	50		
Maximum Junction-to-Case		R _{thJC}	0.85	1.1		

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t ≤ 10 s.

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Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1	2	3	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
	I _{DSS}	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250	
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	60			А
Drain-Source On-State Resistance ^b		V _{GS} = 10 V, I _D = 20 A		0.003		
	Б	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		Ω
	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		
		V _{GS} = 4.5 V, I _D = 15 A		0.005		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S
Dynamic	•					
Input Capacitance	C _{iss}			2650		
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		470		pF
Reverse Transfer Capacitance	C _{rss}			225		
Total Gate Charge ^c	Qg			47	70	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 50 A		10		nC
Gate-Drain Charge ^c	Q _{gd}			12		
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 0.6 Ω		15	25	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50	
Fall Time ^c	t _f			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)		·		
Pulsed Current	I _{SM}				60	А
Diode Forward Voltage	V _{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns

SPECIFICATIONS (T ₁ = 25 °C, unless otherwise noted)	
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Notes:

a. For design aid only; not subject to production testing.

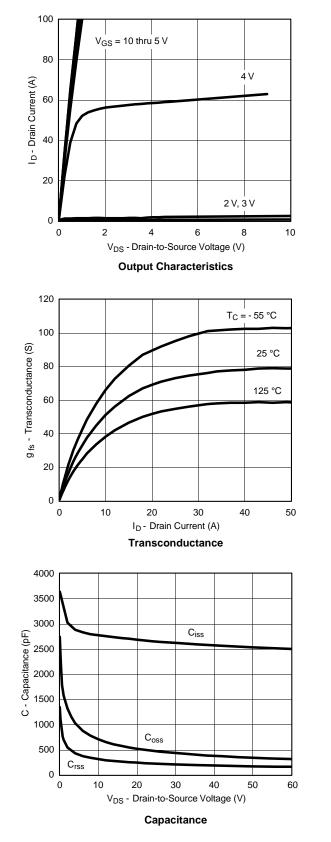
b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

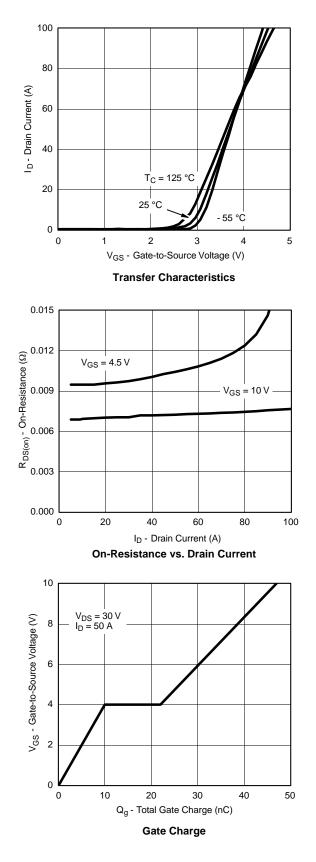
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



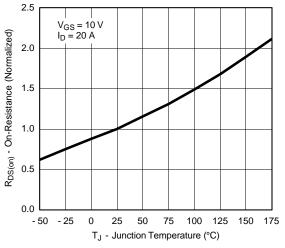
TYPICAL CHARACTERISTICS (25 °C unless noted)



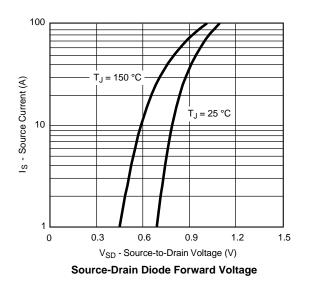




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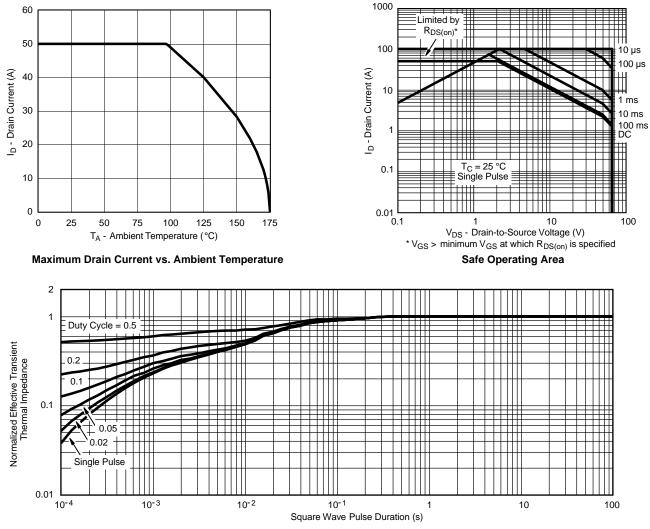


On-Resistance vs. Junction Temperature





THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



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